

Use this form to request wire-bond packaging support for a finalized IC design.

1 | Estimated Turnaround

For general planning, allocate a 6 to 7 week timeline in your project schedule for securing wire-bond packaging. Actual turnaround time may vary depending on the completeness of the submission, required revisions, OSAT review cycles, and PO processing.

2 | Customer Information

Identify the requesting organization, project, and responsible contacts.

Customer / organization *

Project name *

Contacts

Lead Engineer row is required (name + email). Other rows are optional.

Contact	Role	Name	Email	Phone
Lead Engineer *				(xxx) xxx-xxxx
Backup (optional)				(xxx) xxx-xxxx
Business (optional)				(xxx) xxx-xxxx

PO number for packaging

ITAR controlled? *

☐ Yes ☐ No

3 | Tapeout Type

Your selection determines whether wafer handling or singulated-die handling applies.

- ☐ **Option A -- Singulated die from MPW run.**
Foundry diced the wafer and delivered individual die or die in wafer pack.
- ☐ **Option B -- Full wafer(s).**
MOSIS 2.0 handles backgrinding (if needed) and dicing.



4 | Tapeout Type Detail

Fabrication parameters that define the die as received from the foundry.

Foundry *

-- select -- 

PDK selected (e.g., 180nm CL018LP 1P6M) *

Substrate *

-- select -- 

Size *

-- select -- 

Die / substrate thickness (from foundry) *

-- select -- 

Polyimide option *

-- select -- 

Pad termination *

-- select -- 

Metal stack & Pad Options from DM

Die pad 1 convention

-- select -- 

Die available (total) *

5 | Design Detail

Identify the design and the GDS artifact used for wire-bond routing.

Design number * *MOSIS assigns this number.*

200162_0

GDS submission

☐ **Customer GDS -- file name:**

☐ **Mock GDS (pad openings + die perimeter only) -- file name:**

Attached, with correct pad-opening and die-perimeter layers per PDK

6 | Sub-dicing

If the die must be diced into smaller pieces before packaging.

Sub-dicing required? *

☐ Yes ☒ No

If Yes, provide the following

How many sub dies

N/A

How many cut lines

N/A

Cut-line specifications (one per line)

e.g., "full-length vertical 1000 um from the left edge"

N/A

7 | Package Detail

Define each die-and-package configuration, then specify assembly options.

Die Split Table

Rows 1-2 show example grey placeholders -- overwrite with your own values. Row 3 defaults to End; anything below End is ignored.

Split	Design	Description	Package	Lid	Die Qty	Sub-die Qty	Pkg Qty
1	e.g., 200162_0	e.g., POR design	e.g., CLCC68	not required			
2	e.g., 200162_0_SD1	e.g., Sub die 1 design	e.g., Bare die	not required			
3	End			not required			
4				not required			
5				not required			
6				not required			
7				not required			
8				not required			
9				not required			
10				not required			
11				not required			
12				not required			
13				not required			
14				not required			
15				not required			
TOTAL		Validated against Die available (total) and sub-dies from Sections 4 and 6					

Die budget: each Full die = 1 of Die available; each Sub die consumes 1/(sub-dies per die) from Section 6.

Glass type -- required only if a Ceramic Lid with Glass row is selected

Glass type

N/A -- no glass lid

Assembly process options

Die attach *

-- select --

Plasma clean *

3 min Ar plasma

If Other selected above, specify:



1. Wire material and size are dependent on passing assembly DRC.
2. Al wire is compatible with Al-terminated pads.
3. Au wire on Al pads requires a barrier.
4. Allowed wire size depends on layout -- mostly BPO (bond-pad opening).

Submission

Save the completed PDF and reply to the original MOSIS email with the file attached.